PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YOU-SEN WANG	07/31/2009
YUAN YAO	07/31/2009
FENG-WEI DAI	07/31/2009
JI-CUN WANG	07/31/2009
HUI-LING ZHANG	07/31/2009

RECEIVING PARTY DATA

Name:	Tsinghua University
Street Address:	No.1,Qinghua Yuan,Haidian District
City:	Beijing
State/Country:	CHINA

Name:	HON HAI PRECISION INDUSTRY CO., LTD.
Street Address:	66,CHUNG SHAN ROAD
City:	Tu-Cheng,Taipei Hsien
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12578763

CH $40.00 12578763

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	Clifford O. Chi
Total Attachments: 2 source=US24292091012ASM#page1.tif source=US24292091012ASM#page2.tif	

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

1. YOU-SEN WANG, residing at Beijing, China
2. YUAN YAO, residing at Beijing, China
3. FENG-WEI DAI, residing at Beijing, China
4. JI-CUN WANG, residing at Beijing, China
5. HUI-LING ZHANG, residing at Beijing, China
6. ______________, residing at ______________
7. ______________, residing at ______________
8. ______________, residing at ______________

hereby sell(s), assign(s) and transfer(s) unto: **TSINGHUA UNIVERSITY** having a principal place of business at **No.1, Qinghua Yuan, Haidian District, Beijing City, P.R.C.** and **HON HAI PRECISION INDUSTRY CO., LTD.** having a principal place of business at **66,Chung Shan Road, Tu-Cheng City, Taipei Hsien, Taiwan, R.O.C.** hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as THERMAL INTERFACE MATERIAL AND METHOD OF USING THE SAME AND ELECTRONIC ASSEMBLY HAVING THE SAME for which the undersigned

[ ] previously executed --- Ser. No. ______________ and filing date of ______________
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	You-sen Wang YOU-SEN WANG	July 31, 2009 Date	Witness
2.	Yuan Yao YUAN YAO	July 31, 2009 Date	Witness
3.	Feng-Wei Dai FENG-WEI DAI	July 31, 2009 Date	Witness
4.	Ji-Cun Wang JI-CUN WANG	July 31, 2009 Date	Witness
5.	HUI-LING ZHANG HUI-LING ZHANG	July 31, 2009 Date	Witness
6.		Date	Witness
7.		Date	Witness
8.		Date	Witness
9.		Date	Witness